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| Objective |
| Batch name: Process template |
| This process flows is a guideline on how to spin coat, develop and rinse AZ MiR 701 on substrates as Si, SiO2 and Borofloat, using the Spin Track 1 + 2.  |

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| Step Heading | Equipment | **AZ MiR 701 spinning on Si, SiO2, Borofloat** | Comments |
| 1. Pretreatment and spin coat of AZ MiR 701
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| * 1. Pretreatment
 | BHF dip*or*Spin Track 1 + 2 | BHF dip for Si substrates (30 sec, H2O 5 min)Inline HMDS for SiO2 and Borofloat |  |
| * 1. Coat wafers
 | Spin Track 1 + 2  | **Resist:** AZ MiR 701**Softbake:** 1 min @ 90 °C**Spin Track Flows:**T1 MiR 701 2um no HMDS T1 MiR 701 2um with HMDS |  |
| 1. UV Exposure
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| * 1. Exposure
 | KS Aligner | Hard contact**Exposure time:** 25 sec @ 7mW/cm2 |  |
| 1. Post Exposure Bake
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| * 1. Post Exposure Bake
 | Spin Track 1 + 2 | **Post Exposure Bake:** 1 min @ 110 °C**Recipe:** T2 MiR 701 PEB | 1 mm proximity |
| 1. Development, Rinse, and Dry
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| * 1. Development, rinse and dry
 | Developer TMAH UV-lithography | Develop in TMAH for 60sec puddle |  |
| 1. Inspection
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| * 1. Inspection
 | Optical microscope |  |  |